



IPC-SM-782 Library

Supplementary Surface Mount Library for Easy-PC For Windows

IPC-SM-782 Library

The optional IPCSM-782 library contains supplementary component (IPC782.CML) and PCB symbol (IPC782.PSL) libraries for use with any variant of Easy-PC For Windows, version 4.0 or later.

IPC-SM-782 Standard

The Institute for Interconnecting and Packaging Electronic Circuits (IPC) defines a number of standards for electronic devices. One of these is the "Surface Mount Design and Land Pattern Standard" IPC-SM-782, commonly referred to as "IPC782". This specification defines the physical packaging characteristics and land patterns for a range of surface mounted devices. IPC782 is also a useful reference document for general surface mount design techniques, containing sections on design requirements, reliability and testability.

Library Organisation

The PCB symbol library contains approximately 300 surface mount devices in a range of package types. These include chip capacitors, flat packs and chip carriers, in a range of sizes and pin counts, as defined in the IPC-SM-782 standard. The component library contains the same number of items as the PCB symbol library, with a one-to-one correspondence in naming. The items in this library can be used "as is" when creating PCB layouts 'directly' by adding 'generic' components. They can also be copied to new components and edited using the Library tools in Easy-PC For Windows to quickly and easily create your own 'specific' components for particular devices.

Prerequisites For Using the IPC Library

The IPC-SM-782 library works with and requires any Easy-PC For Windows V4 or later version.

Library Features

◆ Discrete Devices

- Chip Capacitors
- Chip Tantalum Capacitors
- Metal Electrode Face (MELF)
- Chip Inductors
- Wire-Wound Chip Inductors
- Chip Resistors
- Small Outline Transistors (SOT) and Diodes (SOD)

◆ Flat Pack Devices

- Ceramic Flat Packs (CFP)
- Ceramic Quad Flat Packs (CQFP)
- Plastic Quad Flat Packs (PQFP)
- Quad Flat Packs (QFP)
- Shrink Quad Flat Pack (SQFP)

◆ Chip Carrier Devices

- Leadless Ceramic Chip Carriers (LCC)
- Plastic Leaded Chip Carriers (PLCC)
- IC Packages
- Small Outline ICs (SOIC)
- Small Outline J-Lead ICs (SOJ)
- Small Outline Packages (SOP)
- Shrink Small Outline ICs (SSOIC)
- Thin Small Outline Packages (TSOP)

◆ Modified Through-Hole Devices

- Butt-Mounted Through-Hole DIPs

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A full detailed listing of the library contents is available on our web site at www.numberone.com